

Special Issue Title: Innovations of Sensor Applications and Related Technologies in IoT

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Special Issue Information

Dear Colleagues,

In recent years, applications of novel sensors and related technologies in electronic and mechanical devices have become rapidly developing fields. The booming economic development in Asia, particularly in leading manufacturing industries such as automobiles, machinery, computers, communications, flat panel displays, semiconductors, and micro/nanoscale technologies, has attracted intense attention among universities, research institutions, and many industrial corporations. Manufacturing is the economic lifeline of a country and has been regarded as a labor-intensive industry. To cut production costs, devices for the Internet of Things (IoT) have been widely developed. IoT systems can be composed of most integrated end devices and facilities, such as intelligent sensors for internal control, industrial systems, mobile terminal systems, floor control

systems, and home intelligent facilities. Smart devices and external control information are utilized with the aim of attracting companies that manufacture high-value-added products in the fields of aerospace, automotives, IT molds, textiles, optoelectronics, watches, medical devices, automation, energy, and semiconductor-related parts and components to drive a country's economy. Therefore, the key to maintaining a competitive advantage in domestic manufacturing in the future is still to promote the development of novel manufacturing and precision-machinery-related technologies. The scope of this Special Issue, "Innovations of Sensor Applications and Related Technologies in IoT," covers fundamental sensors and materials used in electronic, mechanical, and electrical engineering including their synthesis and integration with many elements; the design of electronic and optical devices; sensing technologies; the evaluation of various performance characteristics; and the exploration of their broad applications to industry, environmental control, materials analyses, and so forth. We invite investigators to contribute original research articles, as well as review articles, that will stimulate the continuing efforts to develop electronic and mechanical devices and optical sensors. Potential topics include but are not limited to:

- Electronic devices and mechanical sensors in IoT applications
- Sensing technologies in IoT applications
- Novel sensor-related materials with new electronic and mechanical properties
- Novel sensor-related materials for preparation and applications in IoT applications
- Electronic thin films and coating technologies related to sensors
- Synthesis engineering of novel sensor-related materials
- Novel sensor-related materials for mechatronics in IoT applications
- Novel sensors for IoT applications
- Medical and health applications of sensors
- Remote sensing in IoT applications
- Sensors in robotics

Schedule

Deadline for manuscripts: December 31, 2023

First round of reviews: January 31, 2024

Second round of reviews: March 31, 2024

Acceptance of final papers: April 30, 2024

Publication: May 31, 2024

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 123200 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000–40000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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